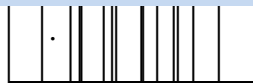
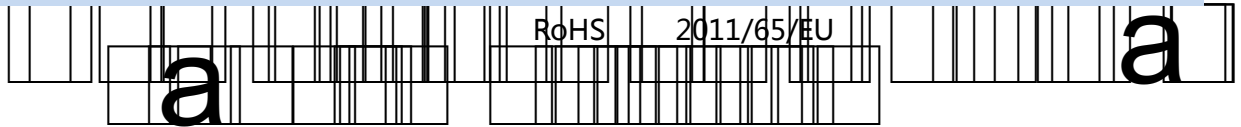
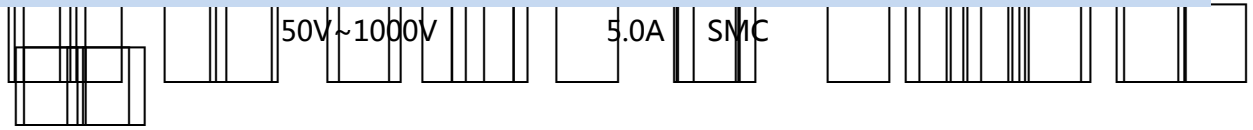
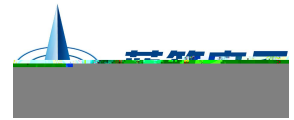
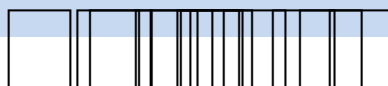
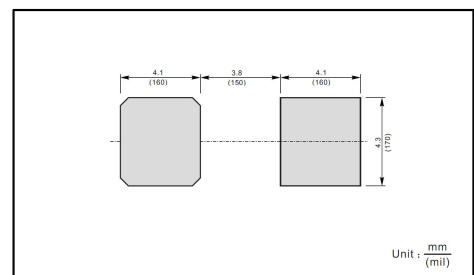


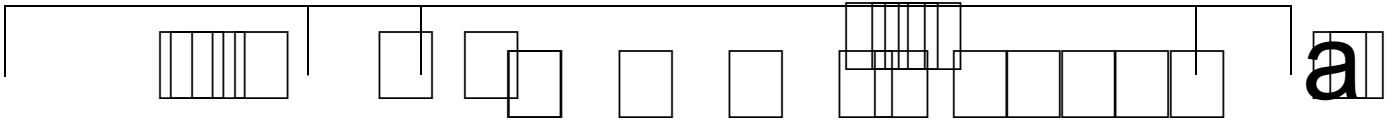
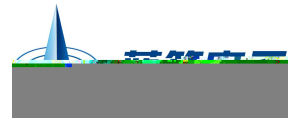


A	2019-7-25	ALL	SMC-RS5AC_RS5MC		
B	2021-2-9	7			



The recommended mounting pad size





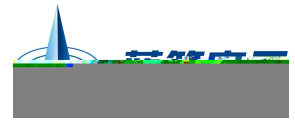


Fig.1 Forward Current Derating Curve

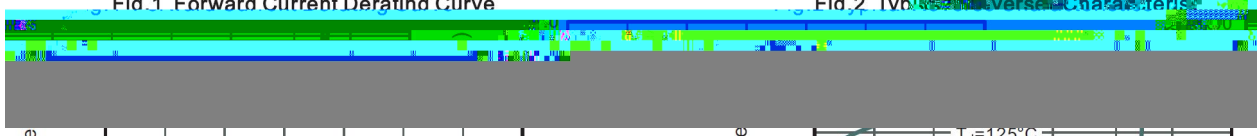


Fig.2 Typical Reverse Current vs. Temperature

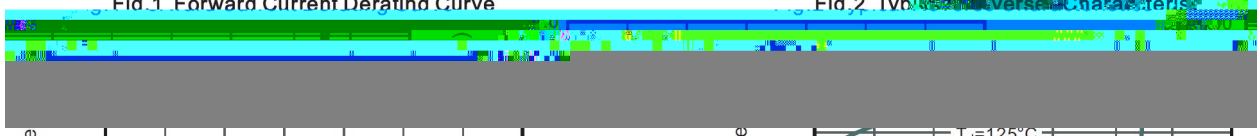


Fig.3 Typical Instantaneous Forward



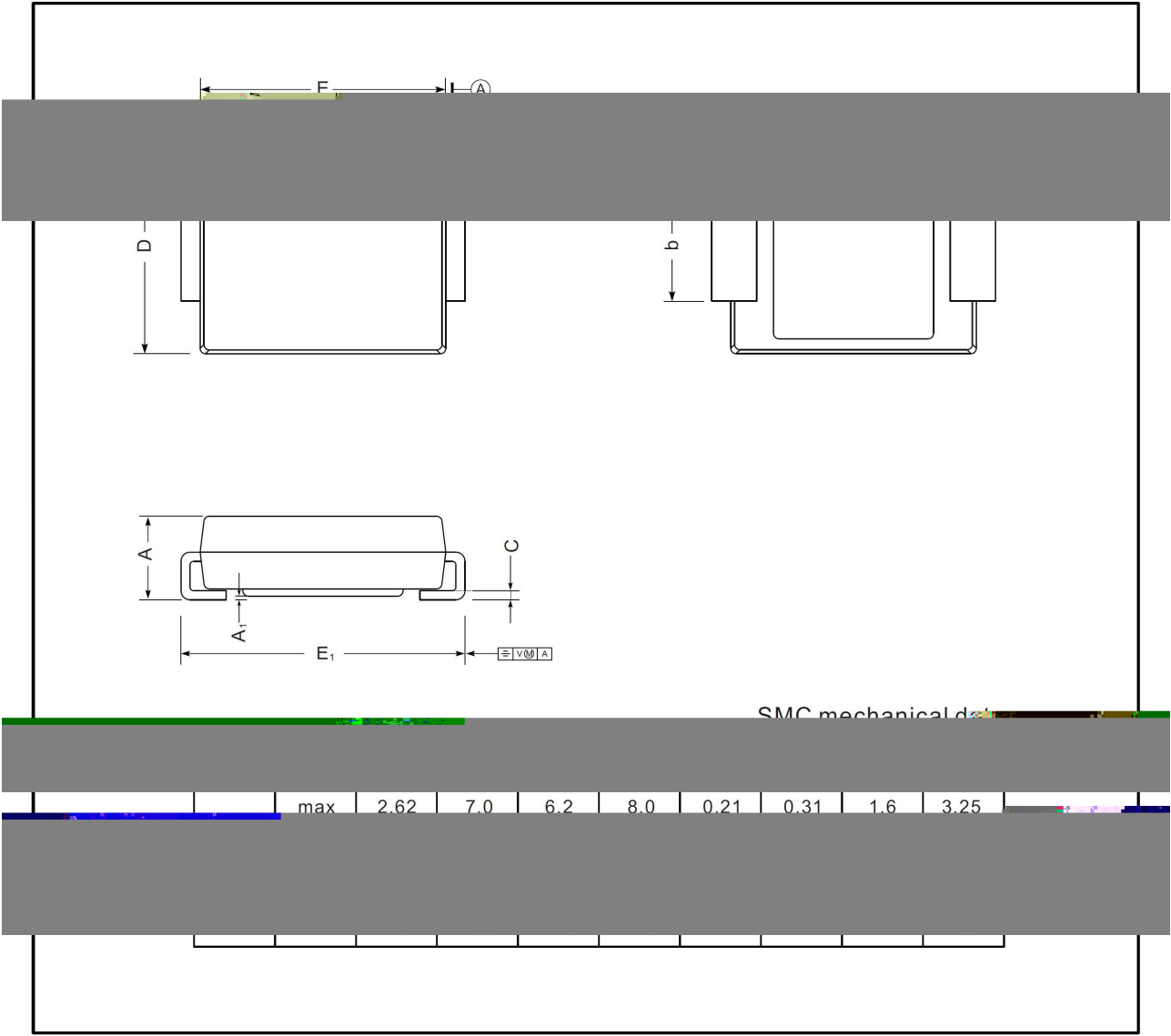
Fig.4 Typical Junction Capacitance

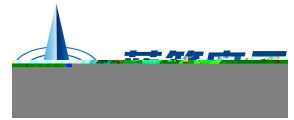


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SMC

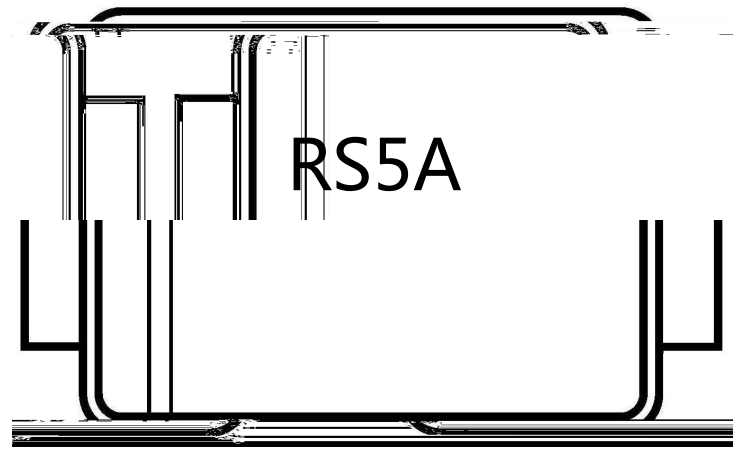
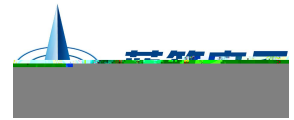




Marking



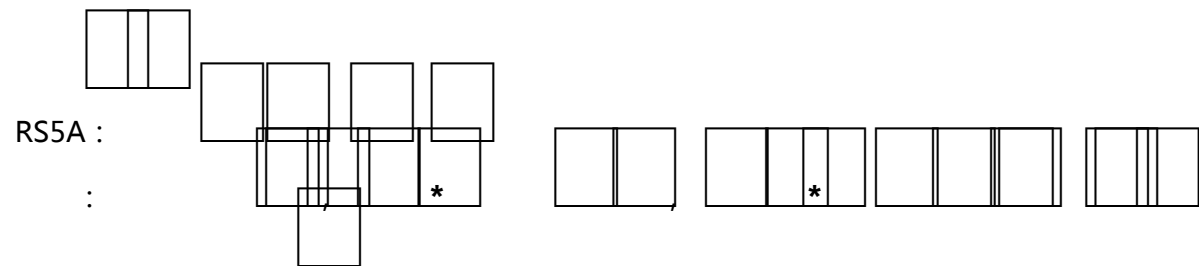
--	--	--	--	--	--	--

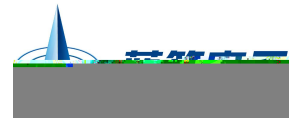


说明：

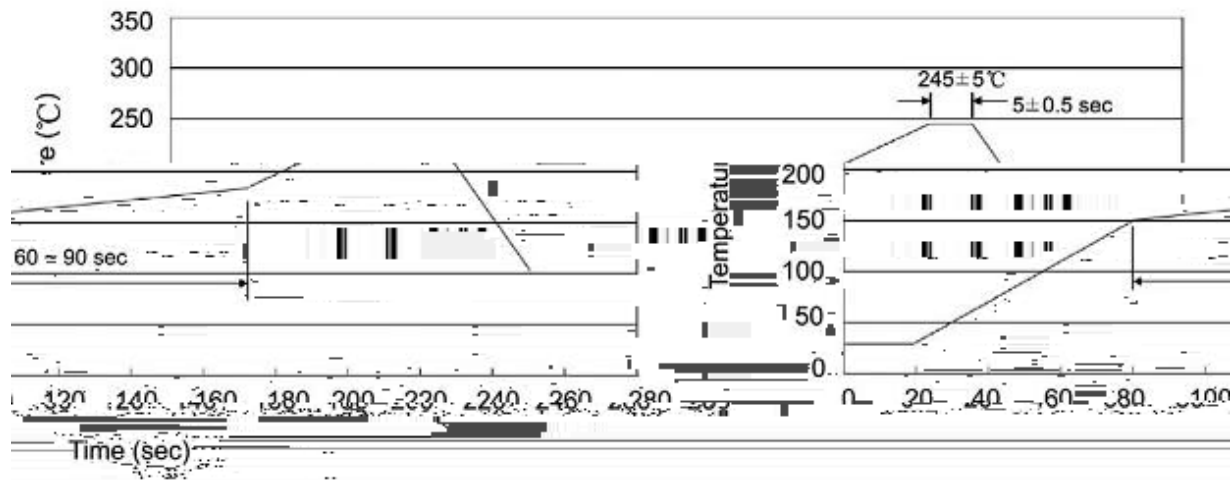
RS5A： 为型号代码

： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码



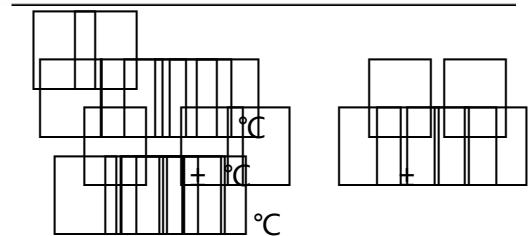


Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 、预热温度 ~ °C, 时间 ~
- 、峰值温度 ± °C, 时间持续为 ±
- 、焊接制程冷却速度为 ~ °C



温度： ± °C 时间： ±



卷盘包装



a

Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box

